

FX10 Temperature rise Test report

October 8th, 2010



HIROSE ELECTRIC

Outline

- Test condition
- Evaluation PCB
- Temperature rise curve
- Derating curve

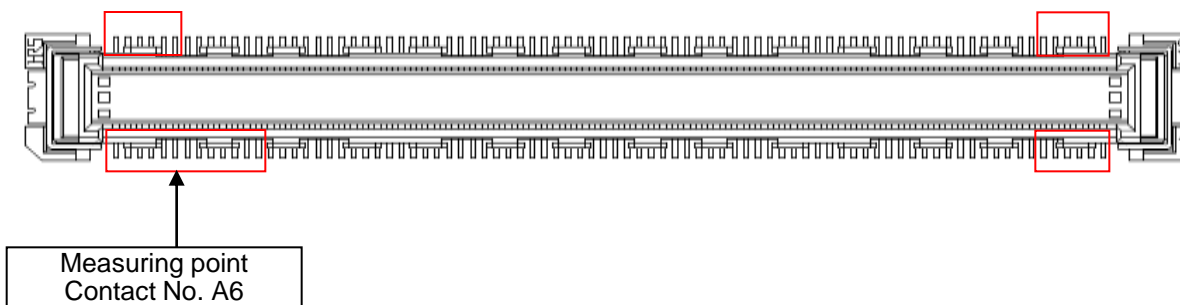
Specimens

FX10A-168P-SV(83)

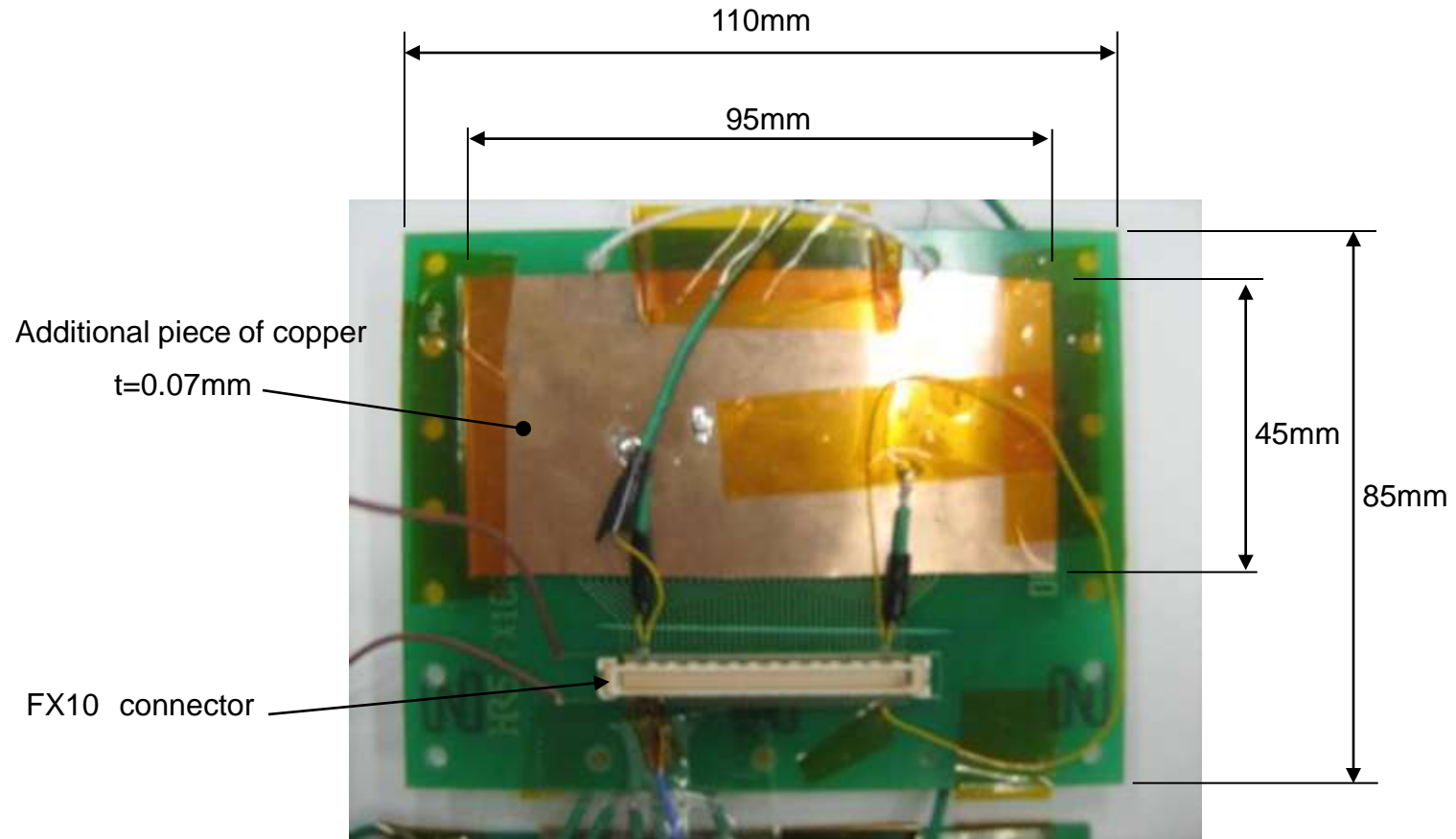
FX10A-168S-SV(83)

Test condition

Temperature rise value	10, 20, 30, 40, 70 and 105 (° C)
Test current	Circuit A: Raising a current from 0.3 A Circuit B: 0.05 A (constant)
Connection method (Series connection)	Circuit A: Contact Nos. A1–A13 and A79-A84 and B1–B6 and B79-B84 Circuit B: Contact Nos. A14-A78 and B7-B78



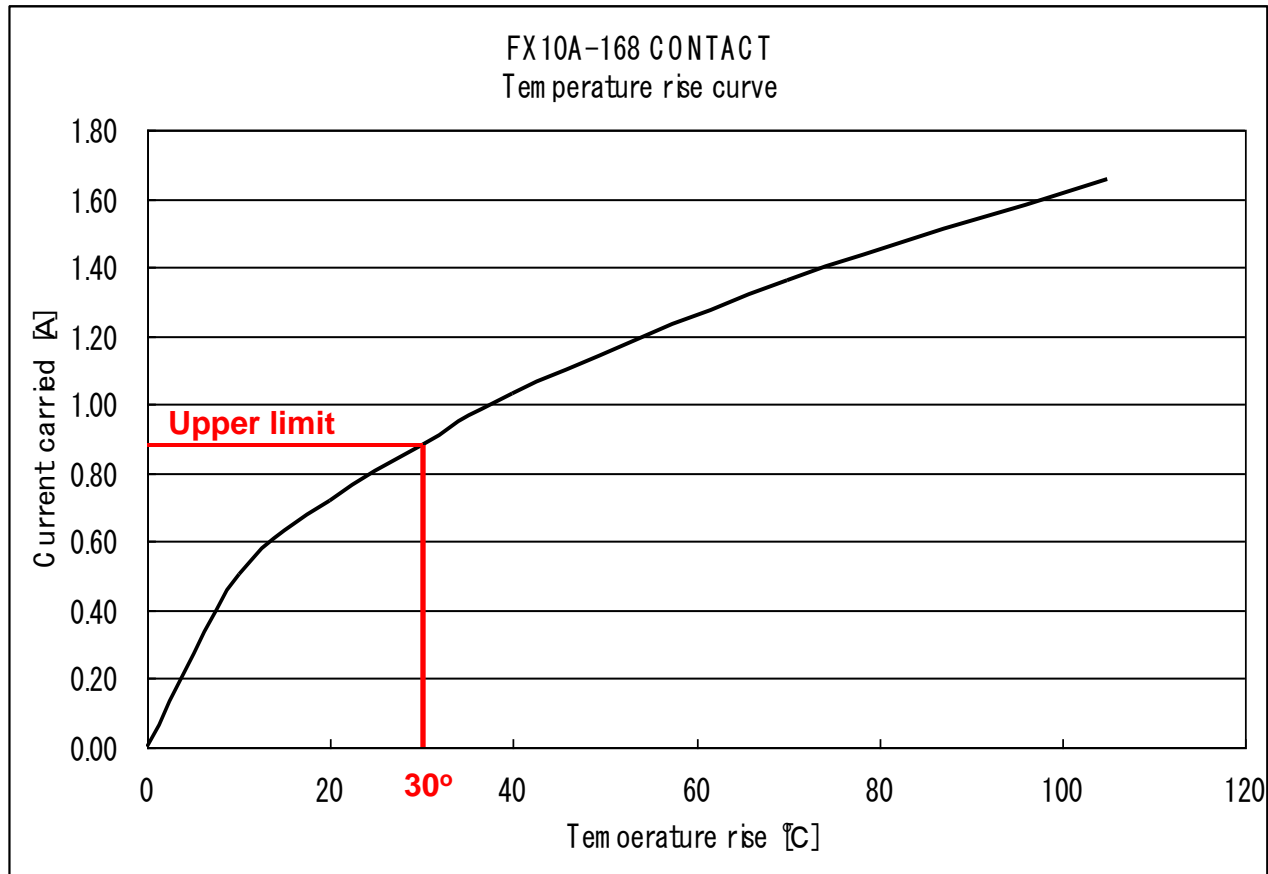
Evaluation PCB



Note.

- 1) FR4 1.6mm thick ,
- 2) 2 layer PCB, No GND plane nor Power plane
- 3) Additional piece of Copper is attached to a PCB to prevent excessive temperature rise on PCBs.

Temperature rise curve



Derating curve

